



**Lead-free, no-clean and halide free solder wire**

**Description:**

Interflux<sup>®</sup> **IF 14-16** lead-free, no-clean solder wire contains no rosin and no halides.

The body of the IF 14 flux carrier can almost fully evaporate during soldering (rather than carbonising).

The residues can easily be removed by hand (brush).

**IF 14-16** is recommended when soldering in **class 3** (IPC-A-610).



Products pictured may differ from the product delivered



**Key properties**

- Low non sticky residue, easily removable by hand
- Reduced contamination of tools, equipment, due to the low flux content
- No colophony fumes
- Classification to IPC and EN: **RE LO**
- Absolutely halogen free
- Long tip-life
- Long product history
- Very good wetting on Cu, Ag, Sn ...

**Availability**

Flux type: IF 14  
Flux content: 1,6% w/w (same volume as 1,4% w/w when using Sn63Pb37)

| alloy                  | melting point | diameters |      |      |      |      |      |      |
|------------------------|---------------|-----------|------|------|------|------|------|------|
|                        |               | 0,20      | 0,35 | 0,50 | 0,70 | 1,00 | 1,50 | 2,00 |
| Sn96,5Ag3Cu0,5         | 217°C—219°C   | ●         | ●    | ●    | ●    | ●    | ●    | ●    |
| Sn96,5Ag3,5            | 221°C         |           | ●    | ●    | ●    | ●    | ●    | ●    |
| Sn95,5Ag3,8Cu0,7       | 217°C-219°C   |           | ●    | ●    | ●    | ●    | ●    | ●    |
| Sn99Ag0,3Cu0,7         | 217°C-227°C   |           | ●    | ●    | ●    | ●    | ●    | ●    |
| Sn99,3Cu0,7            | 227°C         |           | ●    | ●    | ●    | ●    | ●    | ●    |
| Sn99Q <sup>C</sup> (*) | 232°C         |           |      | ●    | ●    | ●    | ●    | ●    |

● = available      ● = upon request

(\*) Sn99Q<sup>C</sup> is an alloy designated for reworking LMPA™-Q solder joints





## Work Instructions

### **Manual soldering**

The advised working temperature is between 320°C and 390°C. For more dense metals like Nickel, the temperature may be elevated to 420°C.

The use of a good soldering station is important. Use a soldering station with a short response time and with enough power for your application.

Choose the correct soldering tip: to reduce the thermal resistance, it is important to create a large contact area with the surfaces to be soldered.

Heat up both the surfaces simultaneously. Slightly touch with the solder wire, the point where soldering tip and the surfaces to be soldered meet (the small quantity of solder ensures

a drastic lowering of the thermal resistance). Add subsequently without interruption, the correct amount of solder close to the soldering tip without touching the tip. This will reduce the risk on flux spitting and premature flux consumption!

## Handling

### **Storage**

Store the solder wire in a clean environment at ambient temperature.

### **Handling**

To avoid spool and wire damage, handle package with care.

### **Safety**

Please always consult the safety datasheet of the product.



## Test results

Conform EN 61190-1-3(2007) and IPC J-STD-004(A)

| Property                    | Result         | Method                        |
|-----------------------------|----------------|-------------------------------|
| <b>Chemical</b>             |                |                               |
| flux designator             | <b>RE L0</b>   | J-STD-004                     |
|                             | <b>F-SW 33</b> | DIN 8511                      |
|                             | <b>1.2.3</b>   | ISO 9454                      |
| qualitative copper mirror   | <b>pass</b>    | J-STD-004 IPC-TM-650 2.3.32   |
| qualitative halide          |                |                               |
| silver chromate (Cl, Br)    | <b>pass</b>    | J-STD-004 IPC-TM-650 2.3.33   |
| spot test (F)               | <b>pass</b>    | J-STD-004 IPC-TM-650 2.3.35.1 |
| quantitative halide         | <b>0,00%</b>   | J-STD-004 IPC-TM-650 2.3.35   |
| <b>Environmental</b>        |                |                               |
| SIR test                    | <b>pass</b>    | J-STD-004 IPC-TM-650 2.6.3.3  |
|                             | <b>pass</b>    | TA-NWT-000078 13.1.4          |
| qualitative corrosion, flux | <b>pass</b>    | J-STD-004 IPC-TM-650 2.6.15   |
| electro chemical migration  | <b>pass</b>    | TA-NWT-000078 13.1.5          |



## Packaging

Spools of 10g, 100g, 500g and 1000g

Not all diameters are available on all spool sizes

Trade name : IF14-16 Lead-Free, Halide Free, No-Clean Solder Wire

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